# NEWS BULLETIN

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**For immediate release**

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## NEXX Systems to Participate in IMEC's Industrial Affiliation Program for Wafer Level Packaging on Cu/Low-k Devices

**Wilmington, MA – January 20, 2003** – NEXX Systems today announced its participation in IMEC's Industrial Affiliation Program (IIAP) to study novel packaging aspects related to Cu/low-k back-end-of-line (BEOL) integrated circuits. These circuits present very specific challenges to packaging technology resulting in novel interconnection and packaging concepts. This three-year program will help provide the foundations for new packaging concepts, new equipment, new materials, and new processes that will, in the near future, address foreseen industrial needs.

As part of its participation in the program, the Nimbus 310 has been installed and accepted by IMEC at its facility in Leuven, Belgium. This system will be used to deposit under bump metallization (UBM) stacks for wafer bumping and thin film redistribution. The Nimbus platform is particularly well suited to address the needs for bumping the advanced Cu/low-k devices IMEC is studying.

“We selected the Nimbus 310 sputtering tool from NEXX Systems for its superior performance and high flexibility, fast wafer change, and ease of use and maintenance, while maintaining a high standard for the quality and uniformity of the deposited films," explained Eric Beyne, director of the EDAS department at IMEC.

**IMEC** (**I**nteruniversity **M**icro**E**lectronics **C**enter) is Europe's largest independent research center in the field of microelectronics, nanotechnology, enabling design methods and technologies for ICT systems. To carry out this research program, IMEC has invested in fully operational Cu BEOL technology, with processes running on state-of-the-art equipment installed in their 200 mm pilot line.

“Participation in this IMEC program is an exciting opportunity for NEXX Systems," stated Richard Post, CEO of NEXX Systems. "In the future, this technology will be mainstream, and our products are well positioned to address both the requirements for high circuit complexity and novel materials. The Nimbus' low cost of ownership is a key factor in meeting industry demands for cost-effective processes in wafer level packaging."

NEXX Systems’ products provide established platforms specifically focused on flip chip advanced packaging. Additional information can be found at: www.nexxsystems.com.

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